

**EC1300HSTS-50.000M-G TR**
[Click part number to visit Part Number Details page](#)
**REGULATORY COMPLIANCE** (Data Sheet downloaded on May 25, 2017)
[Click badges to download compliance docs](#)

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**ITEM DESCRIPTION**50.000MHz  $\pm 100$ ppm 0°C to +70°C**ELECTRICAL SPECIFICATIONS**

|                                       |                                                                                                                                                                                                                                         |
|---------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Nominal Frequency                     | 50.000MHz                                                                                                                                                                                                                               |
| Frequency Tolerance/Stability         | $\pm 100$ ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration) |
| Aging at 25°C                         | $\pm 5$ ppm/year Maximum                                                                                                                                                                                                                |
| Operating Temperature Range           | 0°C to +70°C                                                                                                                                                                                                                            |
| Supply Voltage                        | 3.3Vdc $\pm 10\%$                                                                                                                                                                                                                       |
| Input Current                         | 25mA Maximum                                                                                                                                                                                                                            |
| Output Voltage Logic High (Voh)       | 2.4Vdc Minimum with TTL Load, 2.7Vdc Minimum with LVCMOS Load                                                                                                                                                                           |
| Output Voltage Logic Low (Vol)        | 0.4Vdc Maximum with TTL Load or 0.5Vdc Maximum with LVCMOS Load                                                                                                                                                                         |
| Rise/Fall Time                        | 6nSec Maximum (10% to 90% of waveform)                                                                                                                                                                                                  |
| Duty Cycle                            | 50 $\pm 10$ (%) (Measured at 50% of waveform)                                                                                                                                                                                           |
| Load Drive Capability                 | 15pF LVCMOS Load Maximum                                                                                                                                                                                                                |
| Output Logic Type                     | CMOS                                                                                                                                                                                                                                    |
| Pin 1 Connection                      | Tri-State (High Impedance)                                                                                                                                                                                                              |
| Tri-State Input Voltage (Vih and Vil) | +2.2Vdc Minimum to enable output, +0.8Vdc Maximum to disable output (High Impedance), No Connect to enable output.                                                                                                                      |
| Absolute Clock Jitter                 | $\pm 100$ pSec Maximum                                                                                                                                                                                                                  |
| One Sigma Clock Period Jitter         | $\pm 25$ pSec Maximum                                                                                                                                                                                                                   |
| Start Up Time                         | 10mSec Maximum                                                                                                                                                                                                                          |
| Storage Temperature Range             | -55°C to +125°C                                                                                                                                                                                                                         |

**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

|                              |                                       |
|------------------------------|---------------------------------------|
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C |
| Lead Integrity               | MIL-STD-883, Method 2004              |
| Mechanical Shock             | MIL-STD-202, Method 213, Condition C  |
| Resistance to Soldering Heat | MIL-STD-202, Method 210               |
| Resistance to Solvents       | MIL-STD-202, Method 215               |
| Solderability                | MIL-STD-883, Method 2003              |
| Temperature Cycling          | MIL-STD-883, Method 1010              |
| Vibration                    | MIL-STD-883, Method 2007, Condition A |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION                 |
|-----|----------------------------|
| 1   | Tri-State (High Impedance) |
| 4   | Ground/Case Ground         |
| 5   | Output                     |
| 8   | Supply Voltage             |

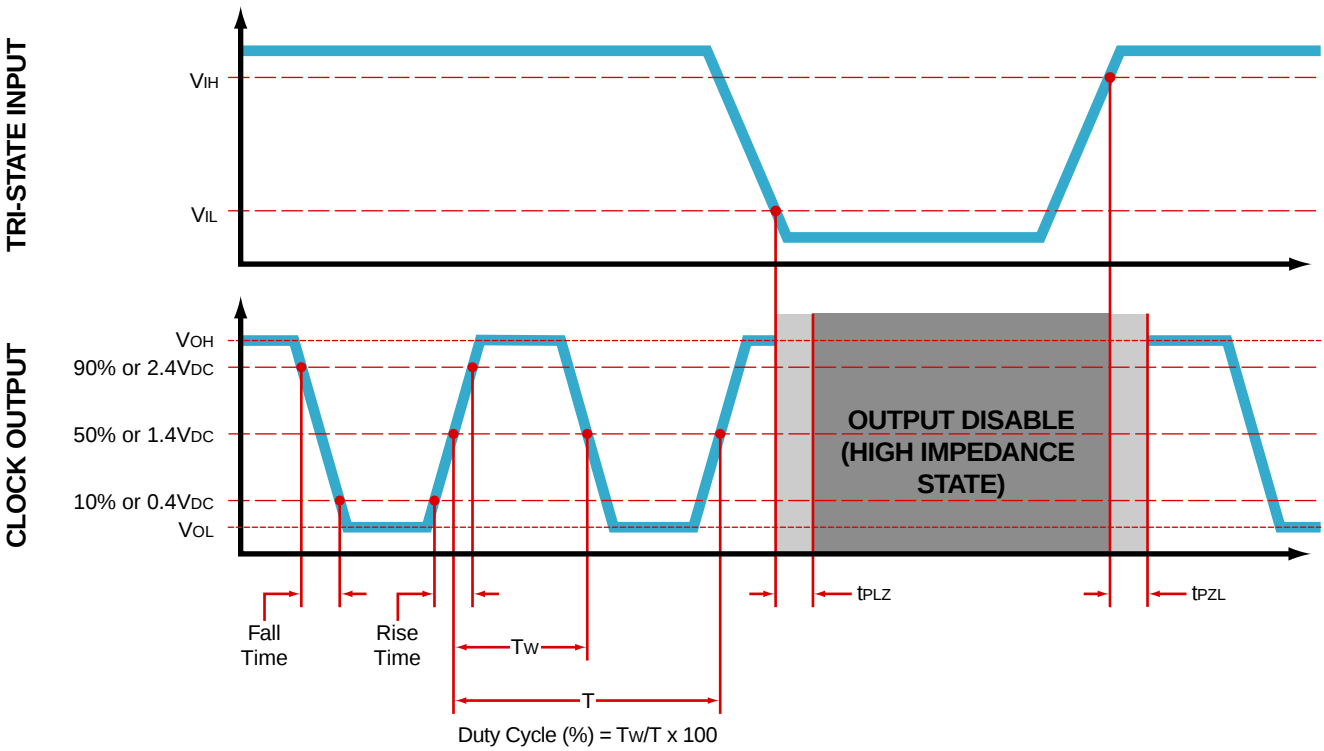
| LINE | MARKING                                                                                    |
|------|--------------------------------------------------------------------------------------------|
| 1    | ECLIPTEK                                                                                   |
| 2    | EC13TS<br>EC13=Product Series                                                              |
| 3    | 50.000M                                                                                    |
| 4    | XXYZZ<br>XX=Ecliptek Manufacturing Code<br>Y=Last Digit of the Year<br>ZZ=Week of the Year |

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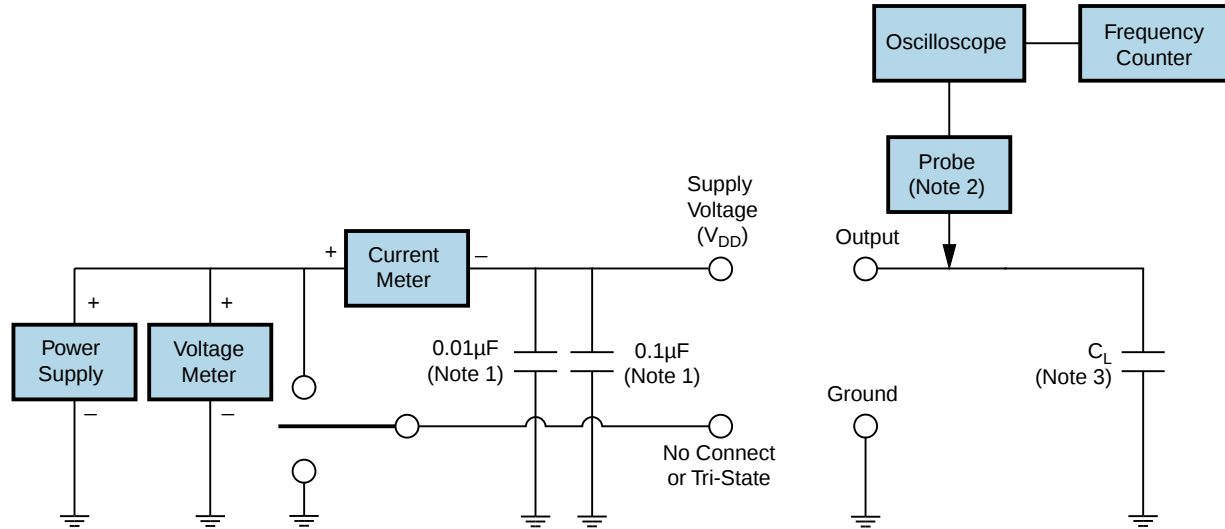
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OUTPUT WAVEFORM & TIMING DIAGRAM





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**Test Circuit for CMOS Output**

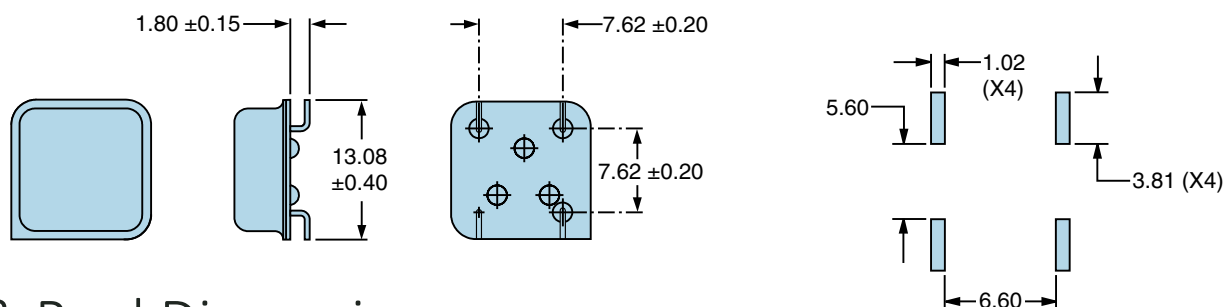
Note 1: An external  $0.1\mu\text{F}$  low frequency tantalum bypass capacitor in parallel with a  $0.01\mu\text{F}$  high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

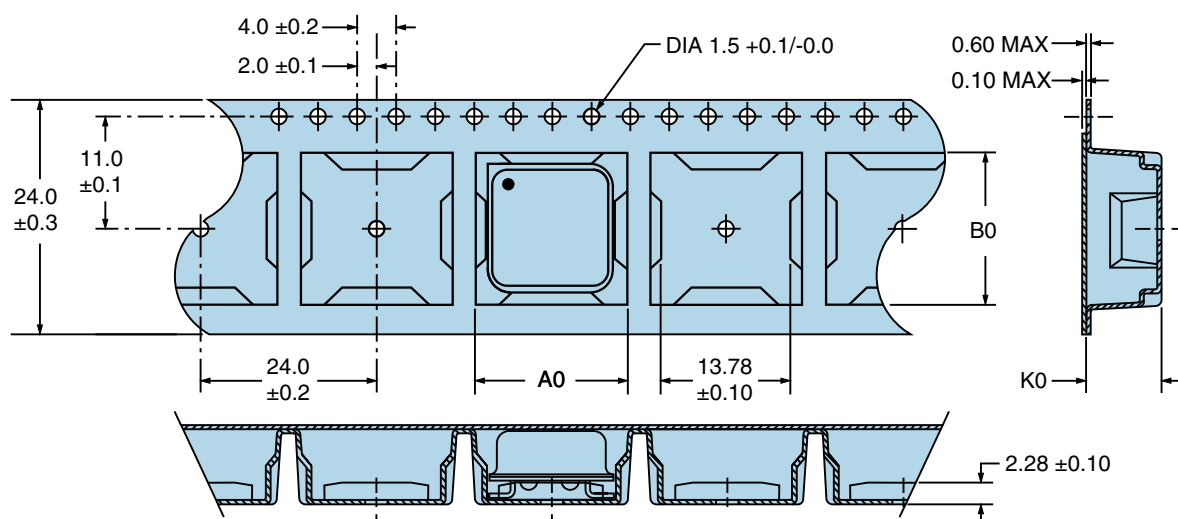
Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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## Gull Wing Option G Dimensions & Recommended Solder Pad Layout



## Tape & Reel Dimensions

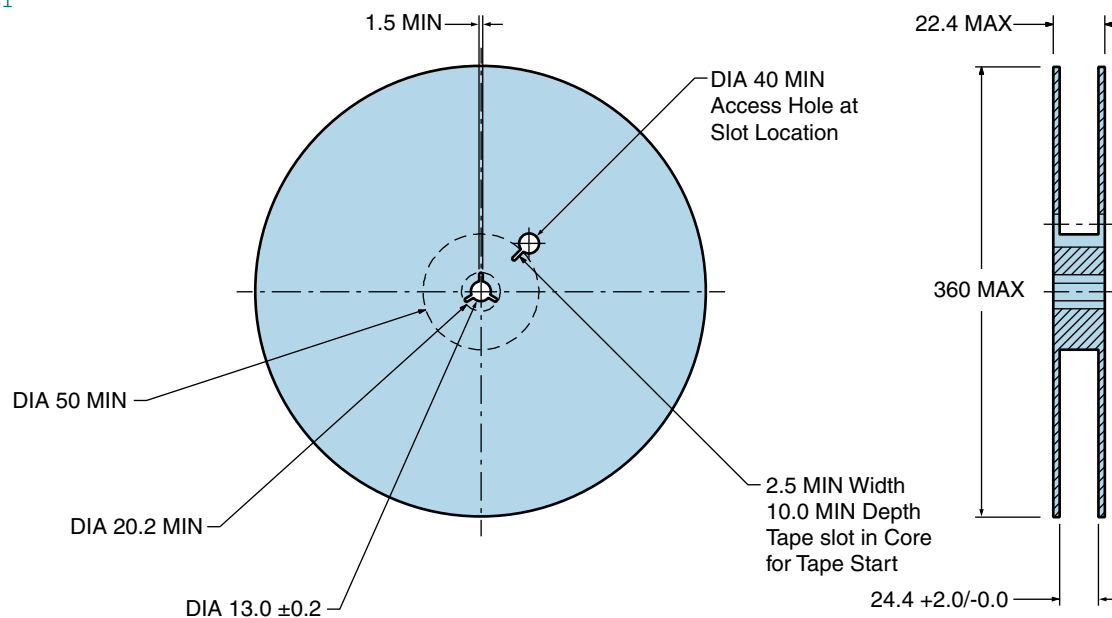


Direction of Unreeling

Quantity Per Reel: 700 Units Maximum

All Dimensions in Millimeters

Compliant to EIA-481



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Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

|                                     |                                      |
|-------------------------------------|--------------------------------------|
| TS MAX to TL (Ramp-up Rate)         | 3°C/Second Maximum                   |
| Preheat                             |                                      |
| - Temperature Minimum (TS MIN)      | 150°C                                |
| - Temperature Typical (TS TYP)      | 175°C                                |
| - Temperature Maximum (TS MAX)      | 200°C                                |
| - Time (ts MIN)                     | 60 - 180 Seconds                     |
| Ramp-up Rate (TL to TP)             | 3°C/Second Maximum                   |
| Time Maintained Above:              |                                      |
| - Temperature (TL)                  | 217°C                                |
| - Time (tL)                         | 60 - 150 Seconds                     |
| Peak Temperature (TP)               | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (TP Target) | 250°C +0/-5°C                        |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds                      |
| Ramp-down Rate                      | 6°C/Second Maximum                   |
| Time 25°C to Peak Temperature (t)   | 8 Minutes Maximum                    |
| Moisture Sensitivity Level          | Level 1                              |

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Recommended Solder Reflow Methods



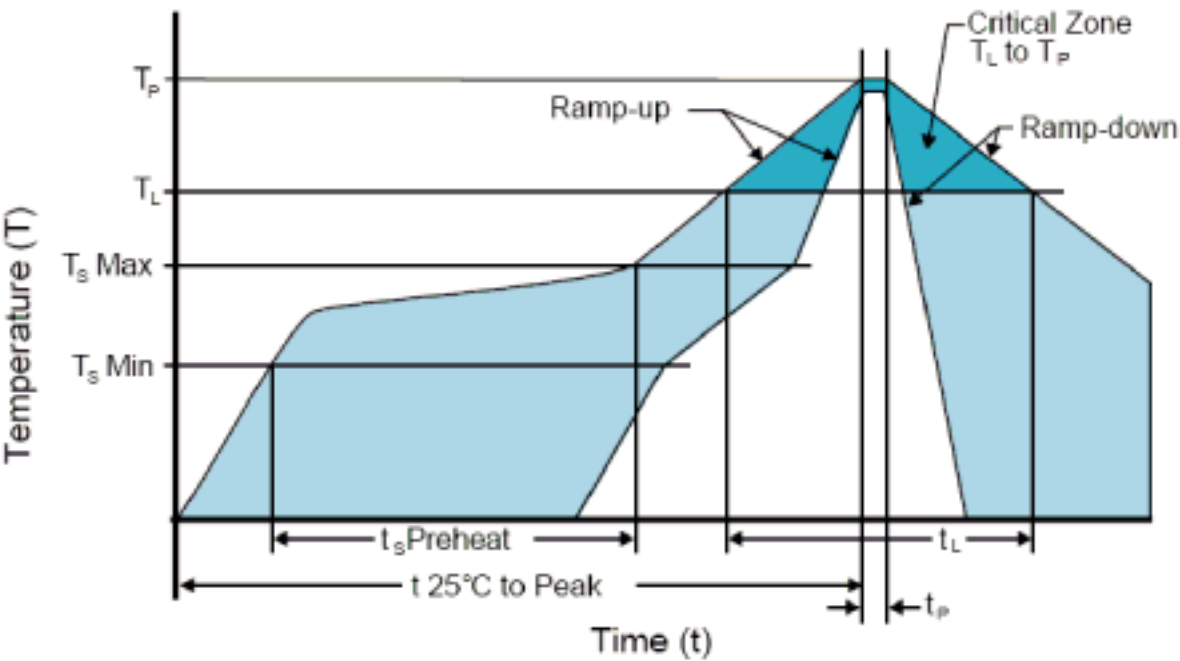
Low Temperature Infrared/Convection 185°C

|                                     |                            |
|-------------------------------------|----------------------------|
| Ts MAX to TL (Ramp-up Rate)         | 5°C/Second Maximum         |
| Preheat                             |                            |
| - Temperature Minimum (Ts MIN)      | N/A                        |
| - Temperature Typical (Ts TYP)      | 150°C                      |
| - Temperature Maximum (Ts MAX)      | N/A                        |
| - Time (ts MIN)                     | 60 - 120 Seconds           |
| Ramp-up Rate (TL to TP)             | 5°C/Second Maximum         |
| Time Maintained Above:              |                            |
| - Temperature (TL)                  | 150°C                      |
| - Time (tL)                         | 200 Seconds Maximum        |
| Peak Temperature (TP)               | 185°C Maximum              |
| Target Peak Temperature (TP Target) | 185°C Maximum 2 Times      |
| Time within 5°C of actual peak (tP) | 10 Seconds Maximum 2 Times |
| Ramp-down Rate                      | 5°C/Second Maximum         |
| Time 25°C to Peak Temperature (t)   | N/A                        |
| Moisture Sensitivity Level          | Level 1                    |

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Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

|                                     |                                                       |
|-------------------------------------|-------------------------------------------------------|
| TS MAX to TL (Ramp-up Rate)         | 5°C/Second Maximum                                    |
| Preheat                             |                                                       |
| - Temperature Minimum (TS MIN)      | N/A                                                   |
| - Temperature Typical (TS TYP)      | 150°C                                                 |
| - Temperature Maximum (TS MAX)      | N/A                                                   |
| - Time (ts MIN)                     | 30 - 60 Seconds                                       |
| Ramp-up Rate (TL to TP)             | 5°C/Second Maximum                                    |
| Time Maintained Above:              |                                                       |
| - Temperature (TL)                  | 150°C                                                 |
| - Time (tL)                         | 200 Seconds Maximum                                   |
| Peak Temperature (TP)               | 245°C Maximum                                         |
| Target Peak Temperature (TP Target) | 245°C Maximum 1 Time / 235°C Maximum 2 Times          |
| Time within 5°C of actual peak (tP) | 5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times |
| Ramp-down Rate                      | 5°C/Second Maximum                                    |
| Time 25°C to Peak Temperature (t)   | N/A                                                   |
| Moisture Sensitivity Level          | Level 1                                               |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.